



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

Datum:

Seite:

**PRINTED CIRCUIT BOARDS**

**01**

**4.11.2001**

**1/1**

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

**04 087 FR4 35 L41.35 P10\_06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_087\_FR4\_35\_L41.35\_p10\_06**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	35 $\mu$	Copper		A1 B
	60 $\mu$	Prepreg	(60 $\mu$ PrePreg-Type: 1080)	
	100 $\mu$	Prepreg	(100 $\mu$ PrePreg-Type: 2125)	
<b>Layer-2</b>	35 $\mu$	Copper		
	410 $\mu$	L-FR4		
<b>Layer-3</b>	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	60 $\mu$	Prepreg		
<b>Layer-99</b>	35 $\mu$	Copper		

© Copyright by Printed Circuit Boards GmbH